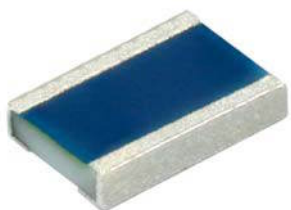


## Precision Wide Terminal Thin Film Chip Resistors



MCW 0406 AT Precision Wide Terminal Resistors are the perfect choice for most fields of modern professional power measurement electronics where reliability, stability, power dissipation, and robust design is of major concern.

Beside extremely high power ratings, the MCW 0406 AT is characterized by extraordinary temperature cycling robustness, verified through extensive testing.

The permissible power rating is specified with 250 mW. Typical applications include power electronics in automotive and industrial appliances.

### FEATURES

- Rated dissipation  $P_{70}$  up to 250 mW
- Resistance range down to 1  $\Omega$
- Superior temperature cycling robustness
- Operating temperature up to 155 °C
- Advanced Sulfur resistance verified according to ASTM B 809
- Superior moisture resistivity
- AEC-Q200 qualified
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

### APPLICATIONS

- Automotive
- Industrial
- High power applications

| TECHNICAL SPECIFICATIONS                                            |                                |
|---------------------------------------------------------------------|--------------------------------|
| DESCRIPTION                                                         | MCW 0406 AT                    |
| Imperial size                                                       | 0406                           |
| Metric size code                                                    | RR1016M                        |
| Resistance range                                                    | 1 $\Omega$ to 100 k $\Omega$   |
| Resistance tolerance                                                | $\pm 0.1 \%$                   |
| Temperature coefficient                                             | $\pm 15$ ppm/K; $\pm 25$ ppm/K |
| Rated dissipation $P_{70}$ <sup>(1)</sup>                           | 0.25 W                         |
| Operating voltage, $U_{\max}$ . AC <sub>RMS</sub> or DC             | 50 V                           |
| Permissible film temperature, $\vartheta_{F \max}$ . <sup>(1)</sup> | 155 °C                         |
| Operating temperature range                                         | -55 °C to 155 °C               |
| Insulation voltage                                                  | 1 min; $U_{\text{ins}}$        |
|                                                                     | Continuous                     |
|                                                                     | 75 V                           |
|                                                                     | 75 V                           |

#### Note

<sup>(1)</sup> Please refer to APPLICATION INFORMATION, see next page.

## APPLICATION INFORMATION

The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly.

These resistors do not feature a lifetime limitation when operated within the limits of rated dissipation, permissible operating voltage and permissible film temperature. However, the resistance typically increases due to the resistor's film temperature over operating time, generally known as drift. The drift may exceed the stability requirements of an individual application circuit and thereby limits the functional lifetime. The designer may estimate the performance of the particular resistor application or set certain load and temperature limits in order to maintain a desired stability.

| MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION                               |           |                              |                              |
|------------------------------------------------------------------------------|-----------|------------------------------|------------------------------|
| OPERATION MODE                                                               |           | STANDARD                     | POWER                        |
| Rated dissipation, $P_{70}$                                                  |           | 0.2 W                        | 0.25 W                       |
| Operating temperature range                                                  |           | -55 °C to 125 °C             | -55 °C to 155 °C             |
| Permissible film temperature, $\vartheta_{F \max.}$                          |           | 125 °C                       | 155 °C                       |
|                                                                              |           | 1 $\Omega$ to 100 k $\Omega$ | 1 $\Omega$ to 100 k $\Omega$ |
| Max. resistance change at $P_{70}$ for resistance range, $\Delta R/R$ after: | 1000 h    | $\leq 0.1 \%$                | $\leq 0.2 \%$                |
|                                                                              | 8000 h    | $\leq 0.2 \%$                | $\leq 0.4 \%$                |
|                                                                              | 225 000 h | $\leq 0.6 \%$                | -                            |

The resistance value is influenced by the resistance of the terminations. The exact resistance value of the soldered part on the PCB may deviate depending on e.g. solder quantity, pad layout, and soldering method. The resistance value of the unmounted part can be verified by a 4-point probe on the top side termination as shown below.

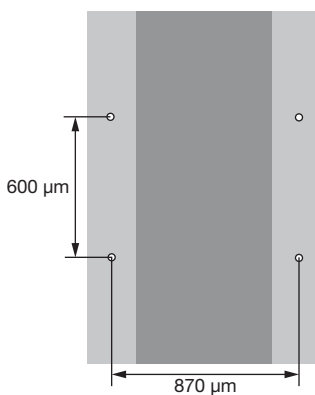


Fig. 1



## TEMPERATURE COEFFICIENT AND RESISTANCE RANGE

| TYPE / SIZE | TCR            | TOLERANCE   | RESISTANCE                    | E-SERIES  |
|-------------|----------------|-------------|-------------------------------|-----------|
| MCW 0406 AT | $\pm 25$ ppm/K | $\pm 0.1$ % | 1 $\Omega$ to 100 k $\Omega$  | E24; E192 |
|             | $\pm 15$ ppm/K | $\pm 0.1$ % | 47 $\Omega$ to 100 k $\Omega$ | E24; E192 |

## PACKAGING

| TYPE / SIZE | CODE | QUANTITY | CARRIER TAPE                                                | WIDTH | PITCH | REEL DIAMETER |
|-------------|------|----------|-------------------------------------------------------------|-------|-------|---------------|
| MCW 0406 AT | P1   | 1000     | Tape and reel<br>cardboard tape acc.<br>IEC 60286-3 Type 1a | 8 mm  | 4 mm  | 180 mm/7"     |
|             | P5   | 5000     |                                                             |       |       | 330 mm/13"    |
|             | PW   | 20 000   |                                                             |       |       |               |

## PART NUMBER AND PRODUCT DESCRIPTION

PART NUMBER: MCW0406MD4641BPW00

|             |   |                     |   |                                  |   |                                                                                                                                                                                                         |   |             |   |                |   |   |   |   |   |   |   |
|-------------|---|---------------------|---|----------------------------------|---|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---|-------------|---|----------------|---|---|---|---|---|---|---|
| M           | C | W                   | 0 | 4                                | 0 | 6                                                                                                                                                                                                       | M | D           | 4 | 6              | 4 | 1 | B | P | W | 0 | 0 |
| TYPE / SIZE |   | VERSION             |   | TCR                              |   | RESISTANCE                                                                                                                                                                                              |   | TOLERANCE   |   | PACKAGING      |   |   |   |   |   |   |   |
| MCW0406     |   | M = AT (Automotive) |   | E = ± 15 ppm/K<br>D = ± 25 ppm/K |   | 3 digit value<br>1 digit multiplier<br><br>MULTIPLIER<br>8 = *10 <sup>-2</sup><br>9 = *10 <sup>-1</sup><br>0 = *10 <sup>0</sup><br>1 = *10 <sup>1</sup><br>2 = *10 <sup>2</sup><br>3 = *10 <sup>3</sup> |   | B = ± 0.1 % |   | P1<br>P5<br>PW |   |   |   |   |   |   |   |

PRODUCT DESCRIPTION: MCW 0406-25 0.1 % AT PW 4K64

|      |      |                                  |             |                 |                |                        |
|------|------|----------------------------------|-------------|-----------------|----------------|------------------------|
| MCW  | 0406 | -25                              | 0.1 %       | AT              | PW             | 4K64                   |
| TYPE | SIZE | TCR                              | TOLERANCE   | VERSION         | PACKAGING      | RESISTANCE             |
| MCW  | 0406 | $\pm 15$ ppm/K<br>$\pm 25$ ppm/K | $\pm 0.1$ % | AT = Automotive | P1<br>P5<br>PW | 4K64 = 4.64 k $\Omega$ |

## Note

- Products can be ordered using either the PART NUMBER or PRODUCT DESCRIPTION.



## DESCRIPTION

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of special metal alloy is deposited on a high grade ceramic substrate ( $\text{Al}_2\text{O}_3$ ) and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly cutting a meander groove in the resistive layer without damaging the ceramics. The resistor elements are covered by a unique protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. This includes full screening for the elimination of products with potential risk of early field failures (feasible for  $R \geq 10 \Omega$ ). Only accepted products are laid directly into the paper tape in accordance with **IEC 60286-3 Type 1a** <sup>(1)</sup>.

## ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using reflow or vapour phase as shown in **IEC 61760-1** <sup>(1)</sup>. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are RoHS compliant; the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. Solderability is specified for 2 years after production or requalification. The permitted storage time is 20 years. The immunity of the plating against tin whisker growth has been proven by extensive testing.

All products comply with the **IEC 62474**, Material Declaration for Products of and for the Electrotechnical Industry.

The dedicated database <sup>(2)</sup>, that list declarable substances, ensures full compliance with the following directives:

- 2000/53/EC End of Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the use of Hazardous Substances Directive (RoHS)
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

## APPROVALS

Where applicable the resistors are tested within the IECQ-CECC Quality Assessment System for Electronic Components to the detail specification **EN 140401-801** which refers to **EN 60115-1**, **EN 140400** and the variety of environmental test procedures of the **IEC 60068** <sup>(1)</sup> series. The detail specification refers to the climatic category 55/125/56, which relates to the "standard operation mode" of this datasheet.

Vishay BEYSCHLAG has achieved "Approval of Manufacturer" in accordance with **IECQ 03-1**. The release certificate for "Technology Approval Schedule" in accordance with **CECC 240001** based on **IECQ 03-3-1**, is granted for the Vishay BEYSCHLAG manufacturing process.

## RELATED PRODUCTS

For an alternative range of TCR and tolerance see the datasheet:

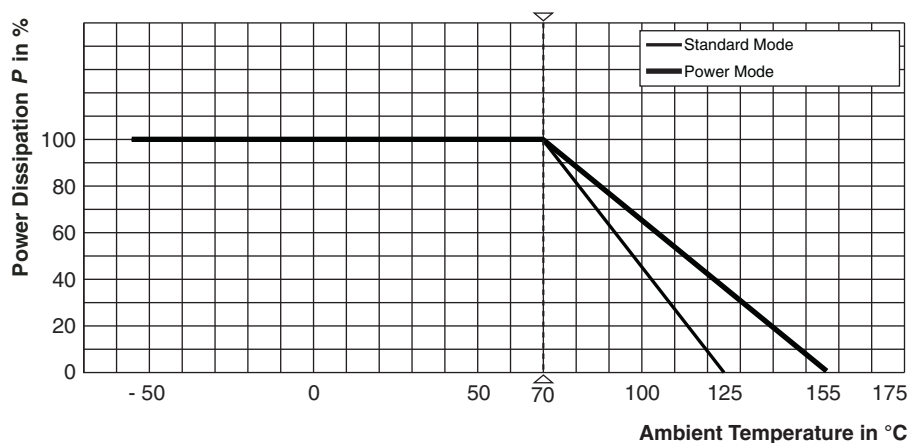
- Professional Wide Terminal Thin Film Chip Resistors ([www.vishay.com/doc?28796](http://www.vishay.com/doc?28796))

## Notes

<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents.

<sup>(2)</sup> IEC 62474 database can be found at <http://std.iec.ch/iec62474>.

## FUNCTIONAL PERFORMANCE



### Derating

#### Note

- For the permissible resistance change in each operation mode please refer to table MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION, above.

## TESTS AND REQUIREMENTS

All tests are carried out in accordance with the following specifications:

EN 60115-1, generic specification

EN 60115-8 (successor of EN 140400), sectional specification

EN 140401-801, detail specification

IEC 60068-2-xx, test methods

The parameters stated in the Test Procedures and Requirements table are based on the required tests and permitted limits of EN 140401-801. The table presents only the most important tests, for the full test schedule refer to the documents listed above. However, some additional tests and a number of improvements against those minimum requirements have been included.

The testing also covers most of the requirements specified by EIA / ECA-703 and JIS-C-5201-1.

The tests are carried out under standard atmospheric conditions in accordance with IEC 60068-1, 4.3, whereupon the following values are applied:

Temperature: 15 °C to 35 °C

Relative humidity: 45 % to 75 %

Air pressure: 86 kPa to 106 kPa (860 mbar to 1060 mbar).

A climatic category LCT / UCT / 56 is applied, defined by the lower category temperature (LCT), the upper category temperature (UCT), and the duration of exposure in the damp heat, steady state test (56 days).

The components are mounted for testing on printed circuit boards in accordance with EN 60115-8, 2.4.2, unless otherwise specified.



## TEST PROCEDURES AND REQUIREMENTS

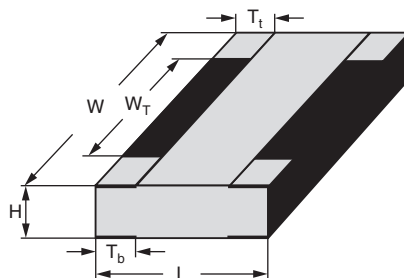
| EN<br>60115-1<br>CLAUSE | IEC<br>60068-2 (1)<br>TEST<br>METHOD             | TEST                                                                   | PROCEDURE                                                                                                                                   | REQUIREMENTS<br>PERMISSIBLE CHANGE ( $\Delta R$ )                 |
|-------------------------|--------------------------------------------------|------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------|
|                         |                                                  |                                                                        | Stability for product types:                                                                                                                |                                                                   |
|                         |                                                  |                                                                        | <b>MCW 0406 AT</b>                                                                                                                          | 1 $\Omega$ to 100 k $\Omega$                                      |
| 4.5                     | -                                                | Resistance                                                             | -                                                                                                                                           | $\pm 0.1 \% R$                                                    |
| 4.8.4.2                 | -                                                | Temperature coefficient                                                | At (20 / -55 / 20) °C and<br>(20 / 155 / 20) °C                                                                                             | $\pm 15$ ppm/K;<br>$\pm 25$ ppm/K                                 |
| 4.25.1                  | -                                                | Endurance at 70 °C:<br>Standard operation mode                         | $U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$ ;<br>whichever is the less severe;<br>1.5 h on; 0.5 h off;<br>70 °C; 1000 h<br>70 °C; 8000 h | $\pm (0.1 \% R + 0.02 \Omega)$<br>$\pm (0.2 \% R + 0.02 \Omega)$  |
|                         |                                                  | Endurance at 70 °C:<br>Power operation mode                            | $U = \sqrt{P_{70} \times R}$ or $U = U_{max.}$ ;<br>whichever is the less severe;<br>1.5 h on; 0.5 h off;<br>70 °C; 1000 h<br>70 °C; 8000 h | $\pm (0.2 \% R + 0.02 \Omega)$<br>$\pm (0.4 \% R + 0.05 \Omega)$  |
| 4.25.3                  | -                                                | Endurance at<br>upper category<br>temperature                          | 125 °C; 1000 h<br>155 °C; 1000 h                                                                                                            | $\pm (0.15 \% R + 0.02 \Omega)$<br>$\pm (0.3 \% R + 0.05 \Omega)$ |
| 4.24                    | 78 (Cab)                                         | Damp heat,<br>steady state                                             | (40 $\pm$ 2) °C; 56 days;<br>(93 $\pm$ 3) % RH                                                                                              | $\pm (0.1 \% R + 0.02 \Omega)$                                    |
| 4.39                    | 67 (Cy)                                          | Damp heat,<br>steady state,<br>accelerated:<br>Standard operation mode | (85 $\pm$ 2) °C<br>(85 $\pm$ 5) % RH<br>$U = \sqrt{0.1 \times P_{70} \times R}$ ;<br>$U \leq 0.3 \times U_{max.}$ ; 1000 h                  | $\pm (0.5 \% R + 0.05 \Omega)$                                    |
| 4.23                    | 2 (Bb)<br>30 (Db)<br>1<br>13 (M)<br>30 (Db)<br>- | Climatic sequence:<br>Standard operation mode:                         |                                                                                                                                             | $\pm (0.25 \% R + 0.05 \Omega)$                                   |
| 4.23.2                  |                                                  | Dry heat                                                               | UCT; 16 h                                                                                                                                   |                                                                   |
| 4.23.3                  |                                                  | Damp heat, cyclic                                                      | 55 °C; 24 h; $\geq 90$ % RH;<br>1 cycle                                                                                                     |                                                                   |
| 4.23.4                  |                                                  | Cold                                                                   | LCT; 2 h                                                                                                                                    |                                                                   |
| 4.23.5                  |                                                  | Low air pressure                                                       | 8.5 kPa; 2 h; (25 $\pm$ 10) °C                                                                                                              |                                                                   |
| 4.23.6                  |                                                  | Damp heat, cyclic                                                      | 55 °C; 24 h; $\geq 90$ % RH;<br>5 cycles                                                                                                    |                                                                   |
| 4.23.7                  | -                                                | DC load                                                                | $U = \sqrt{P_{70} \times R} \leq U_{max.}$ ; 1 min;<br>LCT = -55 °C;<br>UCT = 125 °C                                                        |                                                                   |
| -                       | 1 (Ab)                                           | Storage at low<br>temperature                                          | -55 °C; 2 h                                                                                                                                 | $\pm (0.05 \% R + 0.01 \Omega)$                                   |
| 4.19                    | 14 (Na)                                          | Rapid change of<br>temperature                                         | 30 min at LCT and<br>30 min at UCT;<br>LCT = -55 °C;<br>UCT = 125 °C;<br>1000 cycles                                                        | $\pm (0.25 \% R + 0.05 \Omega)$                                   |
| 4.13                    | -                                                | Short time overload:<br>Standard operation mode                        | $U = 2.5 \times \sqrt{P_{70} \times R}$<br>$\leq 2 \times U_{max.}$ ;<br>whichever is the less severe;<br>5 s                               | $\pm (0.05 \% R + 0.01 \Omega)$                                   |

| TEST PROCEDURES AND REQUIREMENTS |                                              |                                                                |                                                                                                                                                                |                                                                                        |
|----------------------------------|----------------------------------------------|----------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------|
| EN 60115-1<br>CLAUSE             | IEC 60068-2 <sup>(1)</sup><br>TEST<br>METHOD | TEST                                                           | PROCEDURE                                                                                                                                                      | REQUIREMENTS<br>PERMISSIBLE CHANGE ( $\Delta R$ )                                      |
|                                  |                                              |                                                                | Stability for product types:                                                                                                                                   |                                                                                        |
|                                  |                                              |                                                                | <b>MCW 0406 AT</b>                                                                                                                                             | 1 $\Omega$ to 100 k $\Omega$                                                           |
| 4.27                             | -                                            | Single pulse high voltage overload:<br>Standard operation mode | Severity no. 4:<br>$U = 10 \times \sqrt{P_{70} \times R}$ or<br>$U = 2 \times U_{max.}$ ;<br>whichever is the less severe;<br>10 pulses 10 $\mu$ s/700 $\mu$ s | To be determined                                                                       |
| 4.37                             | -                                            | Periodic electric overload:<br>Standard operation mode         | $U = \sqrt{15 \times P_{70} \times R}$ or<br>$U = 2 \times U_{max.}$<br>whichever is the less severe;<br>0.1 s on; 2.5 s off;<br>1000 cycles                   | To be determined                                                                       |
| 4.38                             | -                                            | Electro Static Discharge<br>(Human Body Model)                 | IEC 61340-3-1 <sup>(1)</sup> ;<br>3 pos. + 3 neg.<br>(equivalent to MIL-STD-883,<br>method 3015)<br>500 V                                                      | $\pm (0.5 \% R + 0.05 \Omega)$                                                         |
| 4.22                             | 6 (Fc)                                       | Vibration                                                      | Endurance by sweeping;<br>10 Hz to 2000 Hz;<br>no resonance;<br>amplitude $\leq 1.5$ mm or<br>$\leq 200$ m/s <sup>2</sup> ; 7.5 h                              | $\pm (0.05 \% R + 0.01 \Omega)$<br>no visible damage                                   |
| 4.17.2                           | 58 (Td)                                      | Solderability                                                  | Solder bath method;<br>SnPb40; non-activated flux<br>(215 $\pm$ 3) $^{\circ}$ C; (3 $\pm$ 0.3) s                                                               | Good tinning ( $\geq 95$ % covered);<br>no visible damage                              |
|                                  |                                              |                                                                | Solder bath method;<br>SnAg3Cu0.5 or SnAg3.5;<br>non-activated flux;<br>(235 $\pm$ 3) $^{\circ}$ C; (2 $\pm$ 0.2) s                                            | Good tinning ( $\geq 95$ % covered);<br>no visible damage                              |
| 4.18.2                           | 58 (Td)                                      | Resistance to soldering heat                                   | Solder bath method;<br>(260 $\pm$ 5) $^{\circ}$ C; (10 $\pm$ 1) s                                                                                              | $\pm (0.1 \% R + 0.02 \Omega)$<br>no visible damage                                    |
| 4.29                             | 45 (XA)                                      | Component solvent resistance                                   | Isopropyl alcohol +50 $^{\circ}$ C;<br>method 2                                                                                                                | No visible damage                                                                      |
| 4.32                             | 21 (Ue <sub>3</sub> )                        | Shear (adhesion)                                               | 9 N                                                                                                                                                            | No visible damage                                                                      |
| 4.33                             | 21 (Ue <sub>1</sub> )                        | Substrate bending                                              | Depth 2 mm, 3 times                                                                                                                                            | $\pm (0.05 \% R + 0.01 \Omega)$<br>no visible damage; no open circuit in bent position |
| 4.7                              | -                                            | Voltage proof                                                  | $U_{RMS} = U_{ins.}$ ; (60 $\pm$ 5) s                                                                                                                          | No flashover or breakdown                                                              |
| 4.35                             | -                                            | Flammability                                                   | Needle flame test; 10 s                                                                                                                                        | No burning after 30 s                                                                  |

**Note**

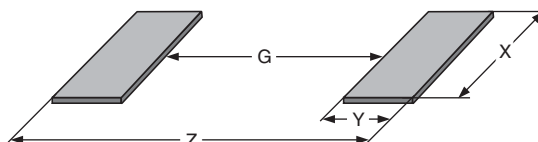
<sup>(1)</sup> The quoted IEC standards are also released as EN standards with the same number and identical contents.

## DIMENSIONS



| DIMENSIONS AND MASS |            |            |            |                     |                     |                     |           |
|---------------------|------------|------------|------------|---------------------|---------------------|---------------------|-----------|
| TYPE                | H (mm)     | L (mm)     | W (mm)     | W <sub>T</sub> (mm) | T <sub>t</sub> (mm) | T <sub>b</sub> (mm) | MASS (mg) |
| MCW 0406 AT         | 0.3 ± 0.05 | 1.0 ± 0.15 | 1.5 ± 0.15 | > 75 % of W         | 0.2 + 0.1/- 0.15    | 0.2 ± 0.1           | 1.9       |

## SOLDER PAD DIMENSIONS



| RECOMMENDED SOLDER PAD DIMENSIONS |                  |        |        |        |
|-----------------------------------|------------------|--------|--------|--------|
| TYPE                              | REFLOW SOLDERING |        |        |        |
|                                   | G (mm)           | Y (mm) | X (mm) | Z (mm) |
| MCW 0406 AT                       | 0.35             | 0.55   | 1.75   | 1.45   |

### Note

- The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or board materials may be required to maintain the reliability of the assembly. Specified power rating above 125 °C requires dedicated heat-sink pads, which to a great extent depends on board materials and design.  
The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters.  
Still, the given solder pad dimensions will be found adequate for most general applications, e.g. those referring to “standard operation mode”. Please note however that applications for “power operation mode” require special considerations for the design of solder pads and adjacent conductor areas.



## Disclaimer

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## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**